Product / Package Information

Package	TSOT
Body Size	N/A
Lead Count	5
Terminal Finish	100Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Mold Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.65 E-03	78.00	780000	36.90	368985
Thermosets	Epoxy resin 1	Proprietary	3.28 E-04	5.50	55000	2.60	26018
Thermosets	Epoxy resin 2	Proprietary	3.28 E-04	5.50	55000	2.60	26018
Other inorganic materials	Metal Hydroxide	Proprietary	3.28 E-04	5.50	55000	2.60	26018
Other inorganic materials	Hardener	Proprietary	2.98 E-04	5.00	50000	2.37	23653
Other inorganic materials	Carbon black	1333-86-4	2.98 E-05	0.50	5000	0.24	2365
Subtotal			5.96 E-03	100.0	1000000	47	473058

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.48 E-03	97.46	974600	35.57	355701
Copper & its alloys	Iron	7439-89-6	1.09 E-04	2.37	23700	0.86	8650
Copper & its alloys	Zinc	7440-66-6	6.90 E-06	0.15	1500	0.05	547
Copper & its alloys	Phosphorus	7723-14-0	9.20 E-07	0.02	200	0.01	73
Subtotal			4.60 E-03	100.0	1000000	36	364971

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.00 E-05	100.00	1000000	0.63	6349
Subtotal			8.00 E-05	100.0	1000000	1	6349

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.35 E-04	100.00	1000000	5.04	50393
Subtotal			6.35 E-04	100.0	1000000	5	50393

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.73 E-04	100.00	1000000	5.34	53408
Subtotal			6.73 E-04	100.0	1000000	5	53408

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.78 E-04	80.00	800000	3.79	37902
Other organic materials	bisphenol-F-(epichlorhydrin); epoxy resin (number average	9003-36-5	8.96 E-05	15.00	150000	0.71	7107
Other organic materials	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	1.49 E-05	2.50	25000	0.12	1184
Other organic materials	Dapsone	80-08-0	1.49 E-05	2.50	25000	0.12	1184
Subtotal			5.97 E-04	100.0	1000000	5	47377

Wire

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	5.60 E-05	100.00	1000000	0.44	4444
Subtotal			5.60 E-05	100.0	1000000	0	4444

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.26 E-02**	**100**	**1000000**

Control ID: MS013406CPKG5528
Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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